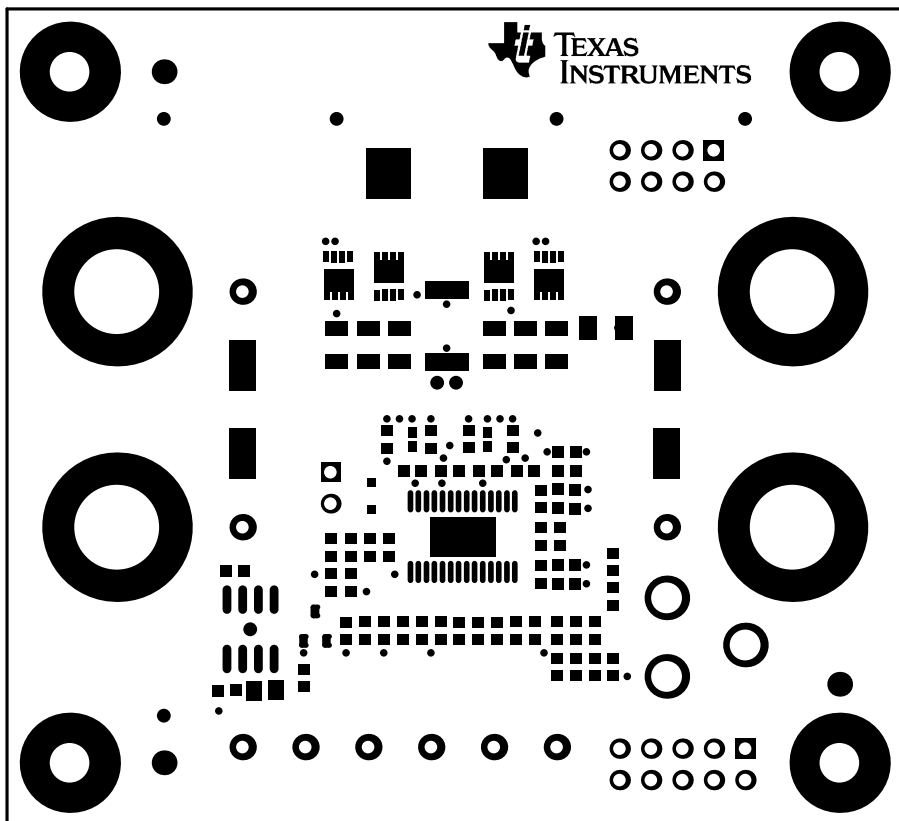
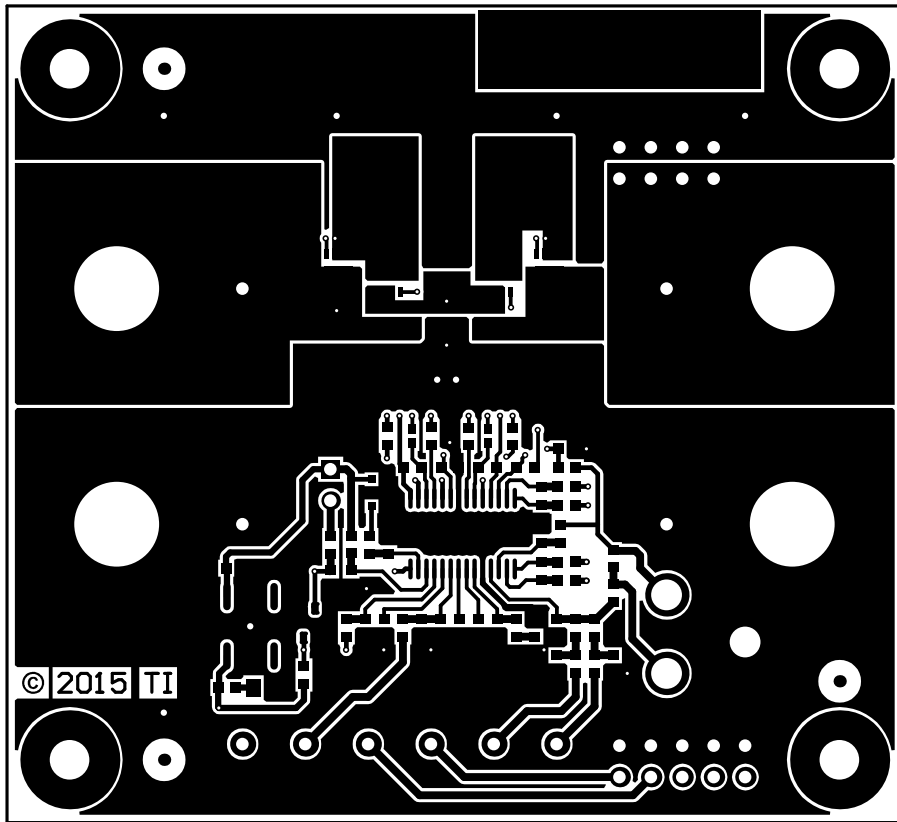


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10624	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 4/7/2015	11:31:38 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10624	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 4/7/2015	11:31:39 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP10624

REV: A

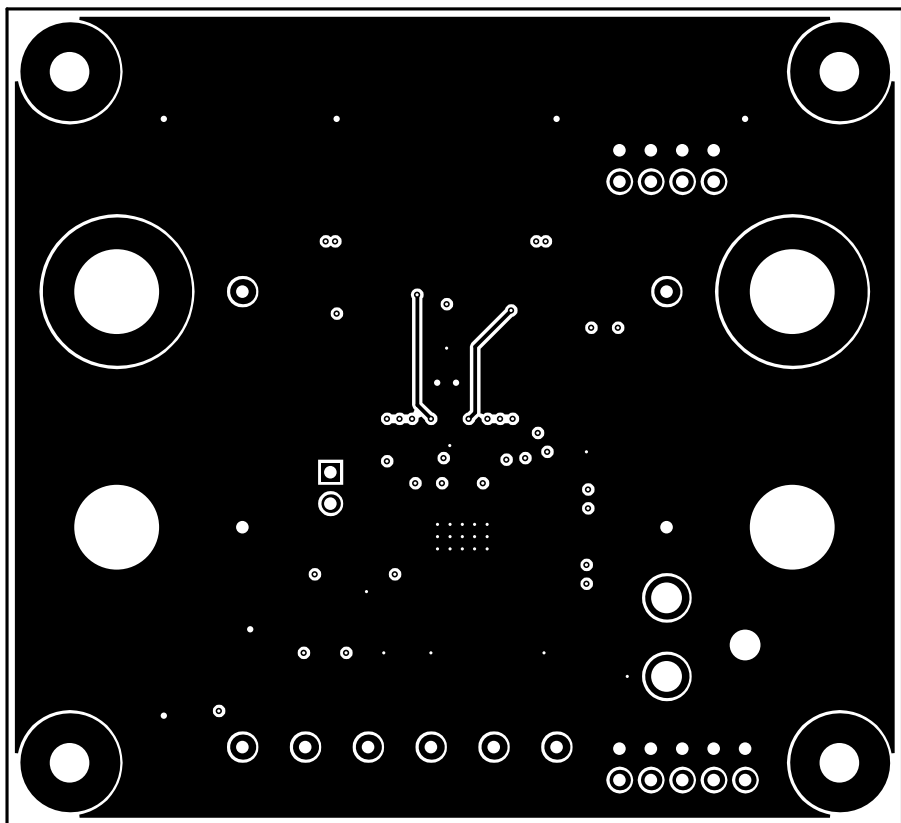
SUN REV: Not In VersionControl

LAYER NAME = Top Layer

PLOT NAME = Top Layer

GENERATED : 4/7/2015 11:31:40 AM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP10624

REV: A

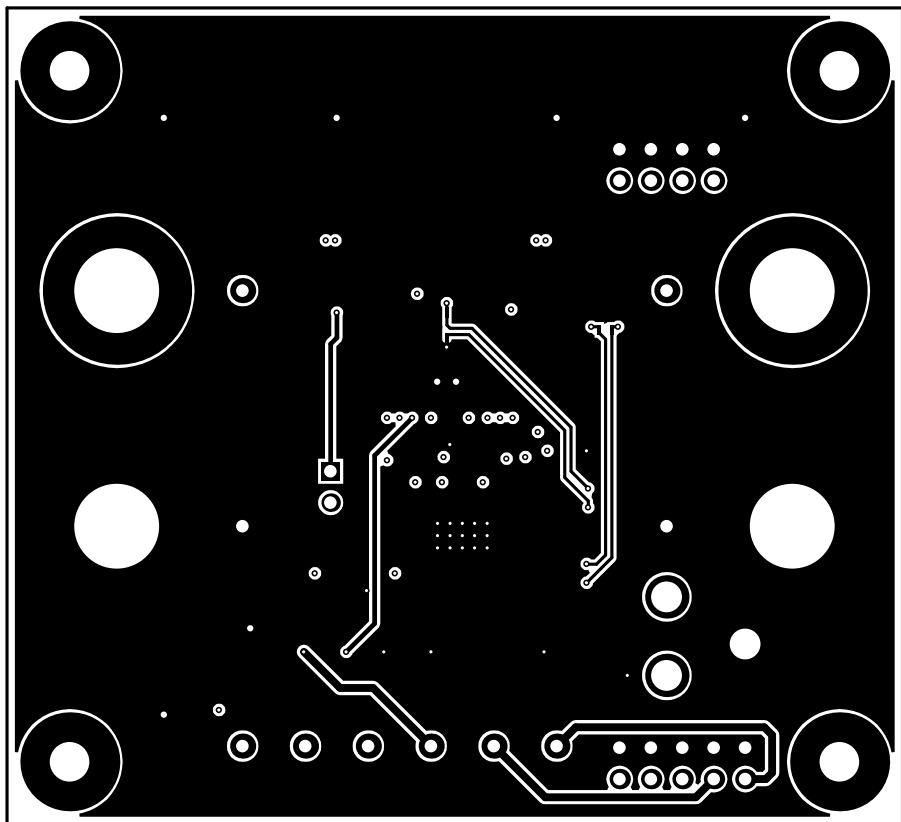
SUN REV: Not In VersionControl

LAYER NAME =

PLOT NAME = MidLayer1

GENERATED : 4/7/2015 11:31:41 AM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP10624

REV: A

SUN REV: Not In VersionControl

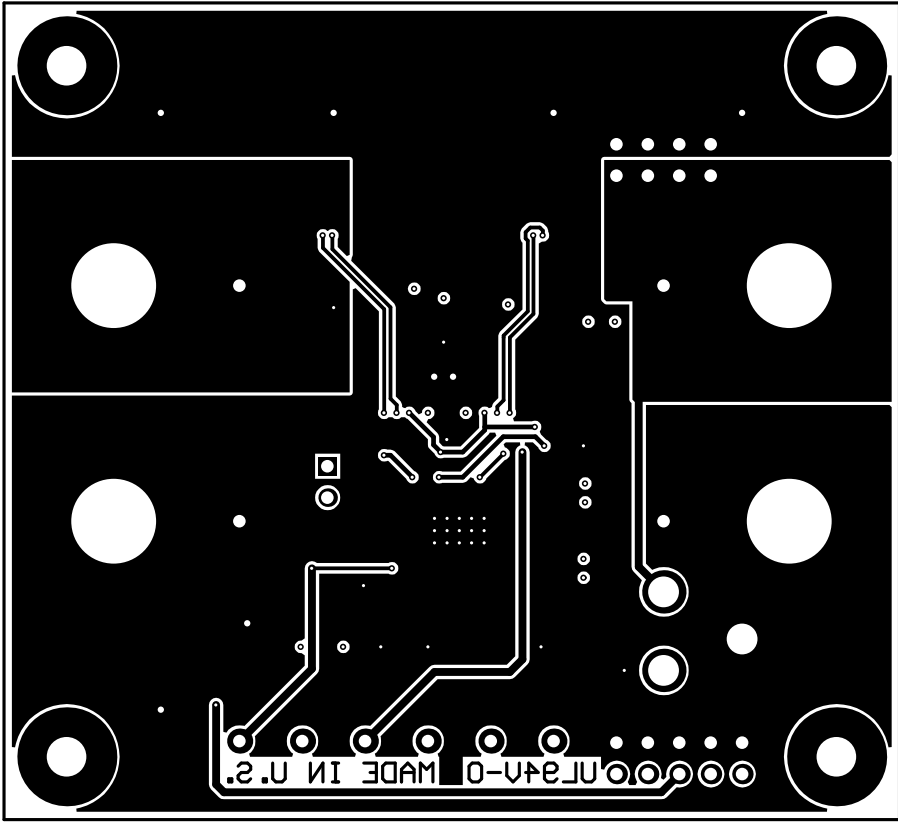
LAYER NAME =

PLOT NAME = MidLayer2

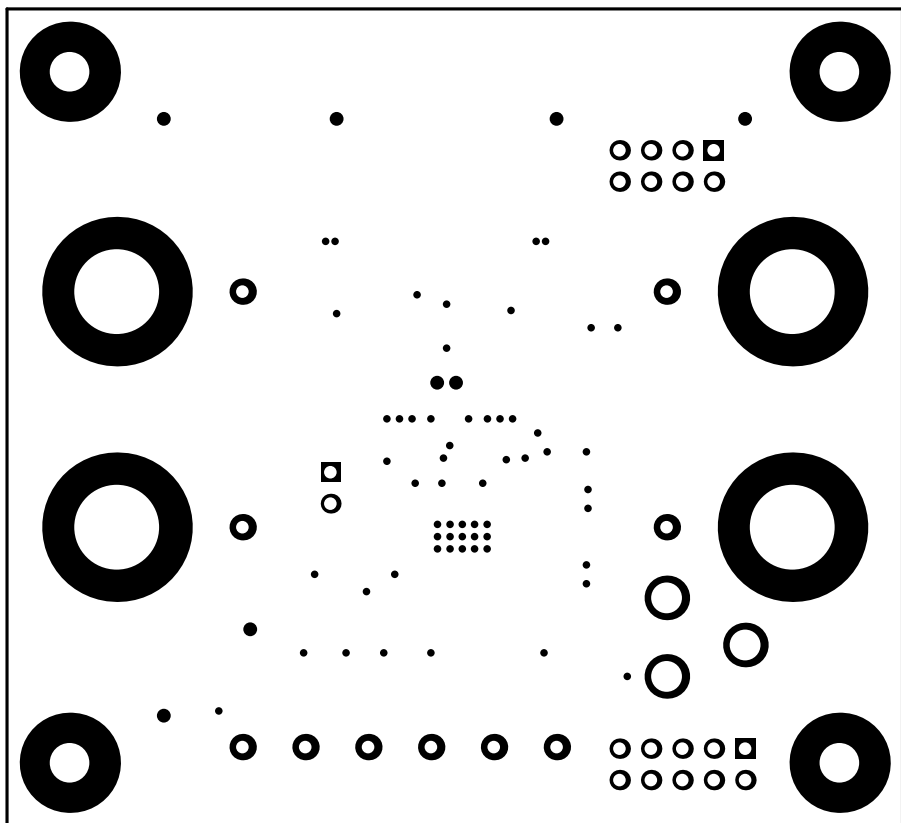
GENERATED : 4/7/2015 11:31:41 AM

TEXAS INSTRUMENTS

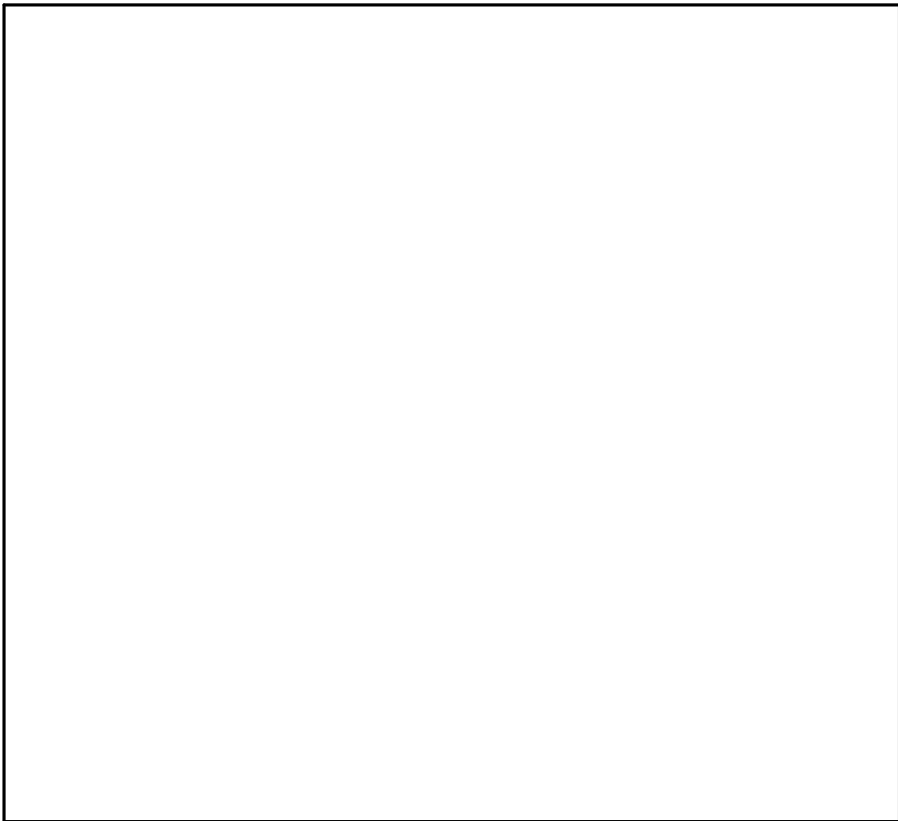
SUN: Not In VersionControl



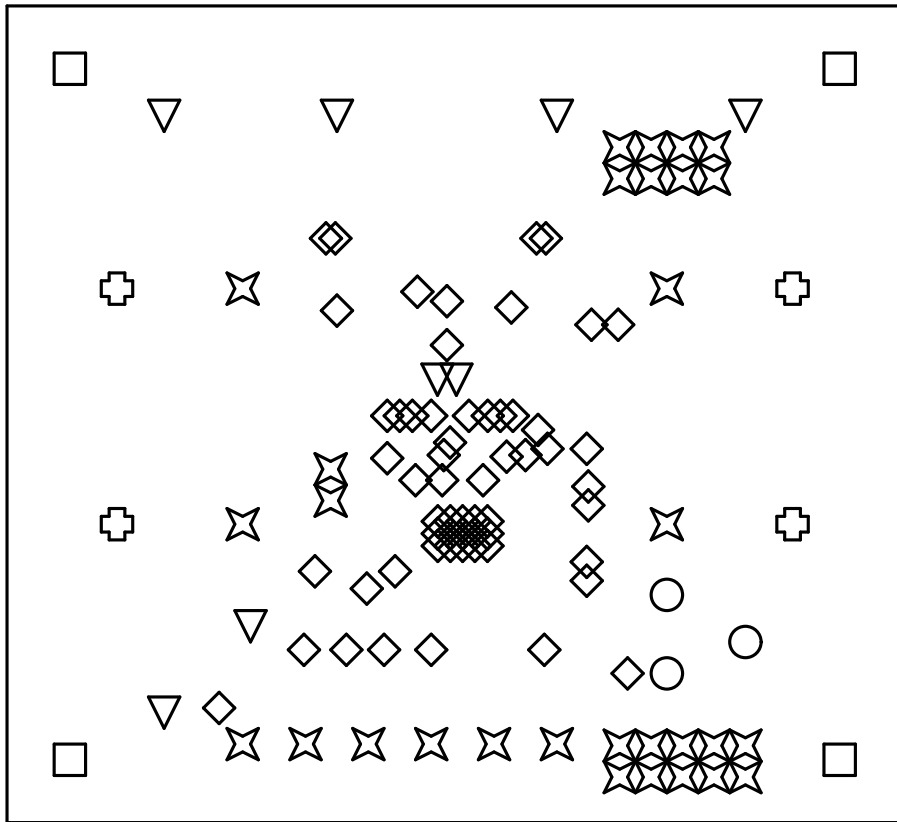
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10624	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 4/7/2015 11:31:42 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10624	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 4/7/2015 11:31:43 AM	TEXAS INSTRUMENTS	

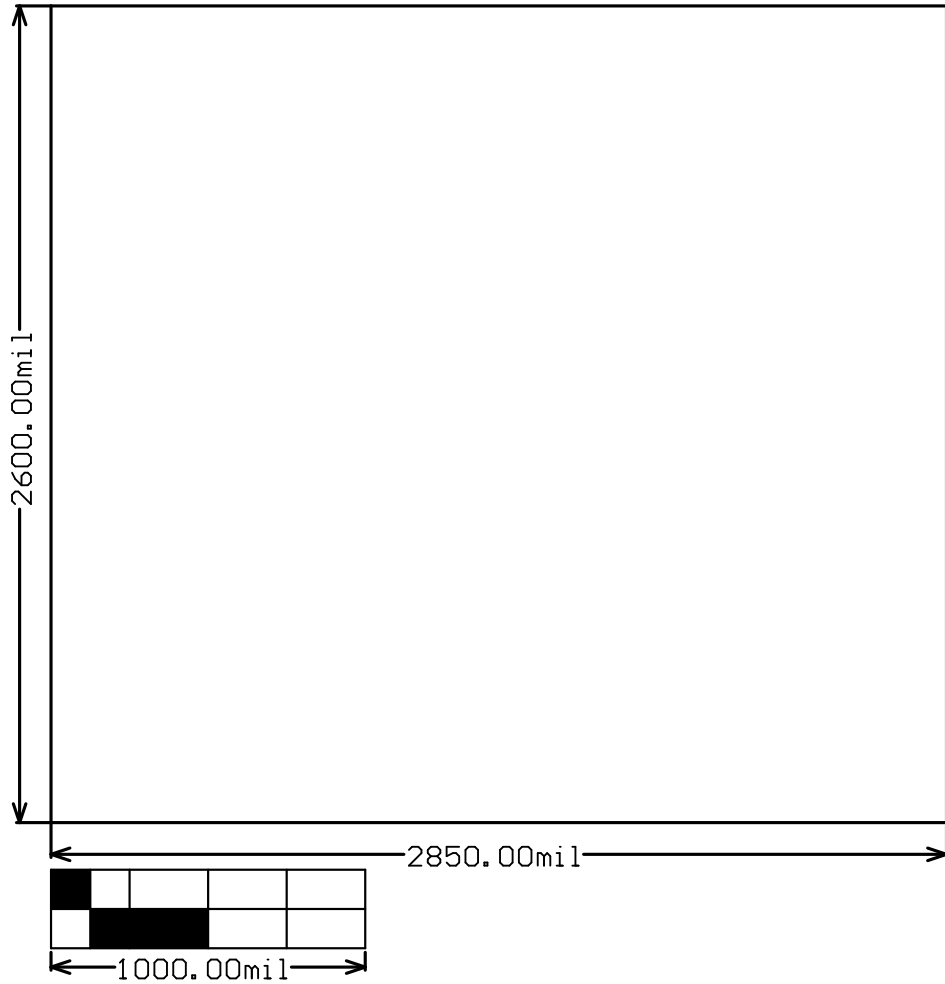


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10624	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 4/7/2015 11:31:44 AM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
◇	59	10.00mil (0.254mm)	PTH	Round
▽	8	20.00mil (0.508mm)	PTH	Round
✖	30	40.00mil (1.016mm)	PTH	Round
○	3	98.43mil (2.500mm)	PTH	Round
□	4	125.98mil (3.200mm)	PTH	Round
⊕	4	270.00mil (6.858mm)	PTH	Round
	108 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10624	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 4/7/2015	11:31:45 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10624	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 4/7/2015 11:31:46 AM	TEXAS INSTRUMENTS	

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